

Amendments to the Claims:

Without prejudice, this listing of the claims replaces all prior versions and listings of the claims in the present application:

Listing of Claims:

1. (Amended) A method for producing a conductive coating on an insulating substrate, comprising:
 - equipping, in selected regions, at least one surface of an electrically insulating substrate with a coating of an electrically highly conductive first metal, the coating being structured as a printed circuit board;
 - cleaning the at least one coated surface;
 - seeding the coating with seeds of a second metal;
 - depositing a layer including an alloy of the second metal onto the coating seeded with the seeds of the second metal; and
 - firing the substrate deposited with the layer of the second metal.
2. (Original) The method as recited in Claim 1, wherein:
 - the substrate includes one of a ceramic and an LTCC, and
 - the first metal includes silver.
3. (Original) The method as recited in Claim 1, wherein:
 - the second metal includes palladium.
4. (Amended) The method as recited in Claim 3, wherein:
 - in the depositing of the layer of the second metal, palladium is deposited at a ratio of from 0.1 to 50% percent by weight of the alloy.
5. (Amended) The method as recited in Claim 3, wherein:
 - in the depositing of palladium, the palladium is deposited in such a way that a concentration of greater than 20% percent by weight palladium in the alloy results.
6. (Original) The method as recited in Claim 1, wherein:
 - the seeding and the depositing are performed according to an electroless procedure.
7. (Original) The method as recited in Claim 1, wherein:
 - the firing is performed at a temperature between 830 and 870°C.
8. (Original) The method as recited in Claim 1, wherein:

the firing is performed at a temperature of 850°C.

9.-10. (Canceled)